SN74AHCT273 クリア搭載、オクタル D タイプ フリップ フロップ

1 特長

- 入力は TTL 電圧互換
- シングル レール出力を備えた 8 つのフリップ フロップ
- 直接クリア入力
- 各フリップ フロップへの個別データ入力
- JESD 17 準拠で 250mA 超のラッチアップ性能
- JESD 22 を上回る ESD 保護
  - 2000V、人体モデル (A114-A)
  - 200V、マシン モデル (A115-A)
  - 1000V、デバイス帯電モデル (C101)

2 アプリケーション

- バッファ / ストレージ レジスタ
- シフト レジスタ
- パターン ジェネレータ
- サーバー
- PC およびノートパソコン
- ネットワーク スイッチ
- メモリ システム
- データベース

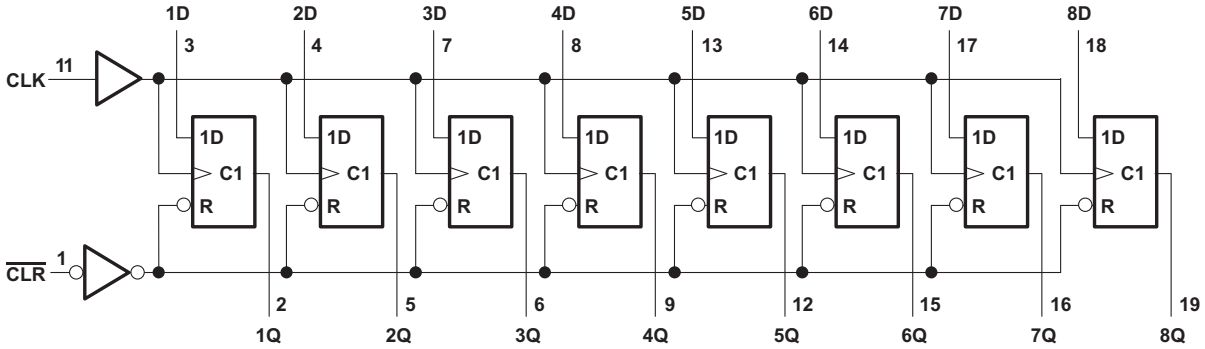
3 概要

これらのデバイスはポジティブ エッジ トリガ D タイプ フリップ フロップで、ダイレクト クリア ($\overline{CLR}$) 入力を備えています。

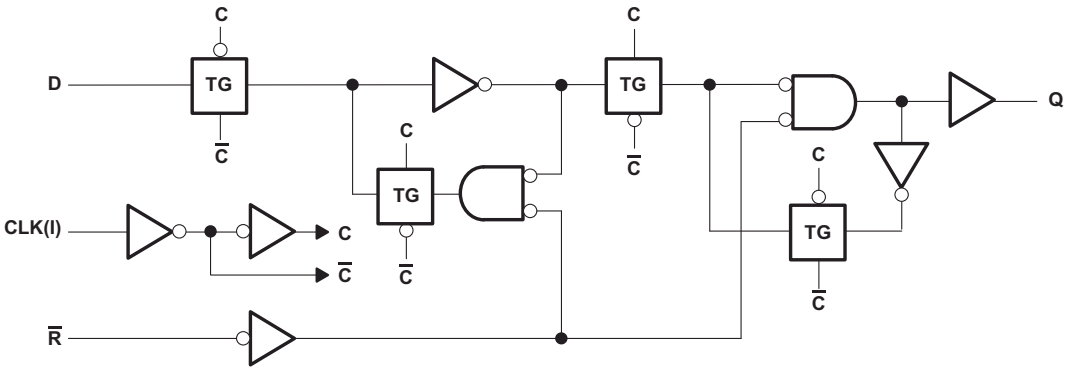
製品情報

部品番号	パッケージ (1)	パッケージ サイズ (2)	本体サイズ (3)
SN74AHCT273	DB (SSOP、20)	7.2mm × 7.8mm	7.2mm × 5.30mm
	DW (SOIC、20)	12.80mm × 10.3mm	12.8mm × 7.5mm
	N (PDIP、20)	24.33mm × 9.4mm	24.33mm × 6.35 mm
	PW (TSSOP、20)	6.50mm × 6.4mm	6.50mm × 4.40mm
	NS (SOP、20)	12.6mm × 7.8mm	12.6mm × 5.3mm

(1) 詳細については、セクション 11 を参照してください。
(2) パッケージ サイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。
(3) 本体サイズ (長さ×幅) は公称値であり、ピンは含まれません。



概略回路図



概略回路図

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4 Pin Configuration and Functions

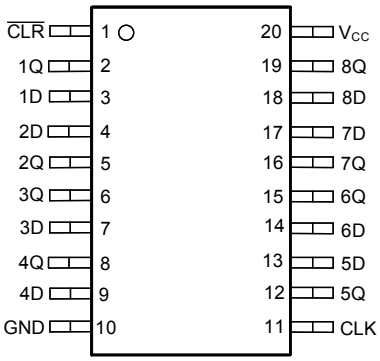


図 4-1. SN74AHCT273 DB, DW, N, NS, or PW Packages; 20-Pin SSOP, SOIC, PDIP, SOP, or TSSOP

表 4-1. Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	$\overline{CLR}$	I	Clear Pin
2	1Q	O	1Q Output
3	1D	I	1D Input
4	2D	I	2D Input
5	2Q	O	2Q Output
6	3Q	O	3Q Output
7	3D	I	3D Input
8	4D	I	4D Input
9	4Q	O	4Q Output
10	GND	—	Ground Pin
11	CLK	I	Clock Pin
12	5Q	O	5Q Output
13	5D	I	5D Input
14	6D	I	6D Input
15	6Q	O	6Q Output
16	7Q	O	7Q Output
17	7D	I	7D Input
18	8D	I	8D Input
19	8Q	O	8Q Output
20	V_{CC}	—	Power Pin

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	7	V
V_I	Input voltage range(2)		–0.5	7	V
V_O	Output voltage range(2)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0		–20	mA
I_{OK}	Output clamp current	V_O < 0 or V_O > V_{CC}		±20	mA
I_O	Continuous output current	V_O = 0 to V_{CC}		±25	mA
	Continuous current through V_{CC} or GND			±75	mA

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 Handling Ratings

			MIN	MAX	UNIT
T_{stg}	Storage temperature range		–65	150	°C
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	0	2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	0	1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)(1)

		SN74AHCT273		UNIT
		MIN	MAX	
V_{CC}	Supply voltage	4.5	5.5	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage	0	5.5	V
V_O	Output voltage	0	V_{CC}	V
I_{OH}	High-level output current		–8	mA
I_{OL}	Low-level output current		8	mA
Δt/Δv	Input transition rise or fall rate		20	ns/V
T_A	Operating free-air temperature	–40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI Application Report, *Implications of Slow or Floating CMOS Inputs* (SCBA004).

5.4 Thermal Information

THERMAL METRIC[1]		SN74AHCT273						UNIT
		DB (SSOP)	DW (SOIC)	DGV (TVSOP)	N (PDIP)	NS (SOP)	PW (TSSOP)	
		20 PINS						
$R_{\theta JA}$	Junction-to-ambient thermal resistance	87.2	81.1	118.1	53.9	77.6	116.8	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	49.1	48.9	33.4	38.8	42.7	58.5	
$R_{\theta JB}$	Junction-to-board thermal resistance	51.8	53.8	59.6	34.7	45.7	78.7	
ψ_{JT}	Junction-to-top characterization parameter	11.6	19.5	1.1	26.9	10.2	12.6	
ψ_{JB}	Junction-to-board characterization parameter	51.2	53.1	58.9	34.7	45.2	77.9	
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	N/A	N/A	N/A	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, (SPRA953).

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	T_A = 25°C			SN74AHCT273		UNIT
				MIN	TYP	MAX	MIN	MAX	
V_{OH}	I_{OH} = –50 µA		4.5 V	4.4	4.5		4.4		V
	I_{OH} = –8 mA			3.94			3.8		
V_{OL}	I_{OL} = 50 µA		4.5 V			0.1		0.1	V
	I_{OL} = 8 mA					0.36		0.44	
I_I	V_I = 5.5 V or GND		0 V to 5.5 V			±0.1		±1	µA
I_{CC}	V_I = V_{CC} or GND	I_O = 0	5.5 V			4		40	µA
ΔI_{CC} [1]	One input at 3.4 V, Other inputs at V_{CC} or GND		5.5 V			1.35		1.5	mA
C_i	V_I = V_{CC} or GND		5 V		2.5	10		10	pF

(1) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

5.6 Timing Requirements

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

			T_A = 25°C		SN74AHCT273		UNIT
			MIN	MAX	MIN	MAX	
t_w	Pulse duration	$\overline{CLR}$ low	5		6		ns
		CLK high or low	5		6.5		
t_{su}	Setup time	Data before CLK ↑	5		5		ns
		$\overline{CLR}$ before CLK ↑	2.5		2.5		
t_h	Hold time, data after CLK ↑		0		0		ns

5.7 Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Load Circuit and Voltage Waveforms)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN74AHCT273		UNIT
				MIN	TYP	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	75(1)	120(1)		65		MHz
			C_L = 50 pF	50	75		45		
t_{PHL}	$\overline{CLR}$	Q	C_L = 15 pF		7.5(1)	10(1)	1	11.6	ns
t_{PLH}	CLK	Q	C_L = 15 pF		5.5(1)	7.5(1)	1	8.8	ns
t_{PHL}					5.8(1)	8.2(1)	1	10	
t_{PHL}	$\overline{CLR}$	Q	C_L = 50 pF		8.5	11	1	12.6	ns
t_{PLH}	CLK	Q	C_L = 50 pF		6.5	8.5	1	9.8	ns
t_{PHL}					6.8	9.2	1	11	
$t_{sk(o)}$			C_L = 50 pF			1(2)		1	ns

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.
(2) On products compliant to MIL-PRF-38535, this parameter does not apply.

5.8 Noise Characteristics

V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C(1)

PARAMETER		SN74AHCT273			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		7.6		V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		–0.48		V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}	4.4			V
$V_{IH(D)}$	High-level dynamic input voltage	2			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.8	V

(1) Characteristics are for surface-mount packages only.

5.9 Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	No load,	f = 1 MHz	27	pF

5.10 Typical Characteristics

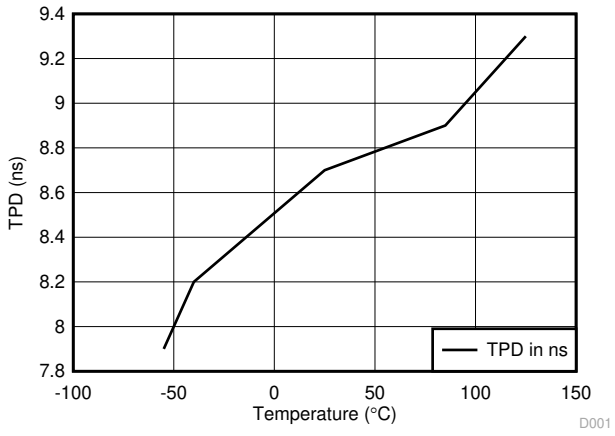
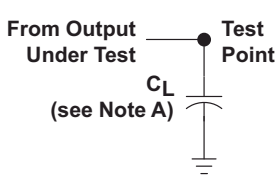
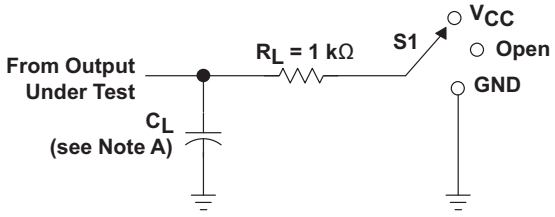


図 5-1. TPD vs Temperature

6 Parameter Measurement Information

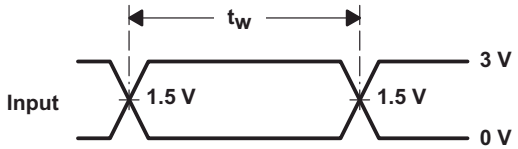


LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

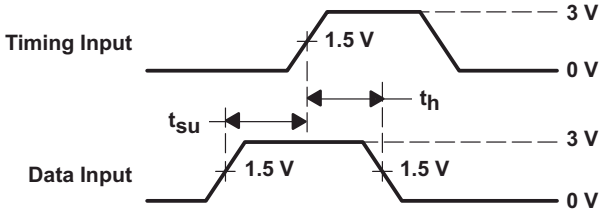


LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS

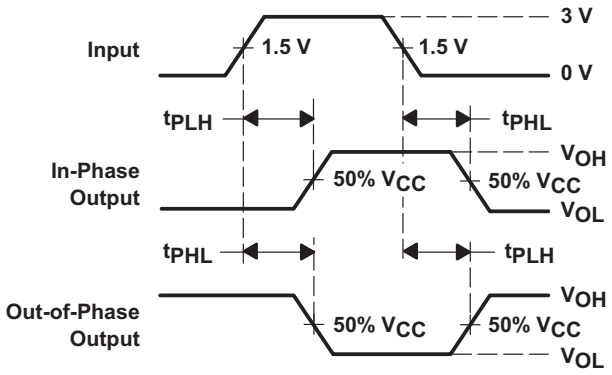
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}



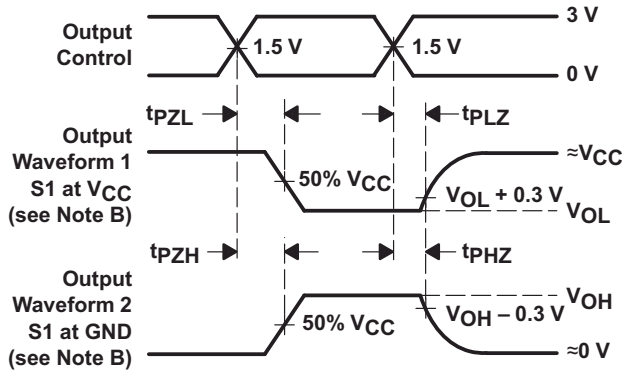
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
D. The outputs are measured one at a time with one input transition per measurement.

図 6-1. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

These circuits are positive-edge-triggered D-type flip-flops with a direct clear ($\overline{CLR}$) input. Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When CLK is at either the high or low level, the D input has no effect at the output.

The inputs are TTL compatible with V_{IL} at 0.8 V and V_{IH} at 2 V. This feature allows the use of these devices as up translators in a mixed 3.3 V to 5 V system environment.

7.2 Functional Block Diagrams

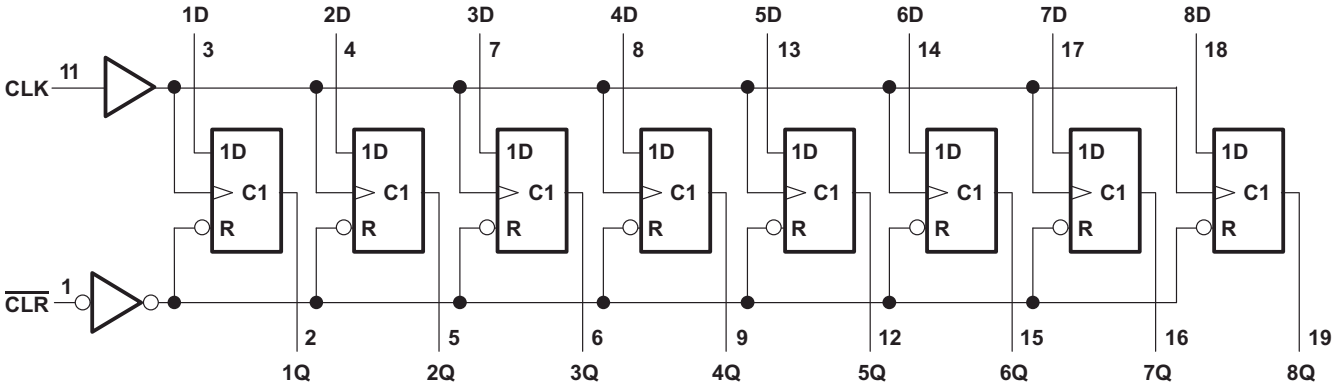


図 7-1. Logic Diagram (Positive Logic)

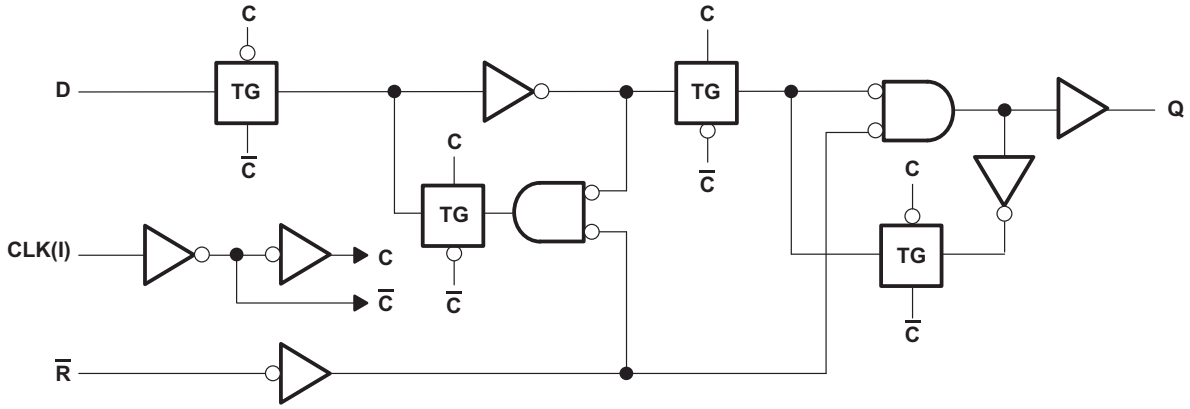


図 7-2. Logic Diagram, Each Flip-flop (Positive Logic)

7.3 Feature Description

- Allow up voltage translation from 3.3 V to 5 V
  - Inputs accept TTL voltage levels
- Slow edge rates minimize output ringing

7.4 Device Functional Modes

表 7-1. Function Table (Each Flip-flop)

INPUTS			OUTPUT Q
$\overline{CLR}$	CLK	D	
L	X	X	L
H	↑	H	H
H	↑	L	L
H	L	X	Q_0

8 Application and Implementation

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

8.1 Application Information

The SNx4AHCT273 is a low-drive CMOS device that can be used for a multitude of applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The inputs are TTL compatible. This feature makes it ideal for translating up from 3.3 V to 5 V. 図 8-2 shows the reduction in ringing compared to higher drive parts such as AC.

8.2 Typical Application

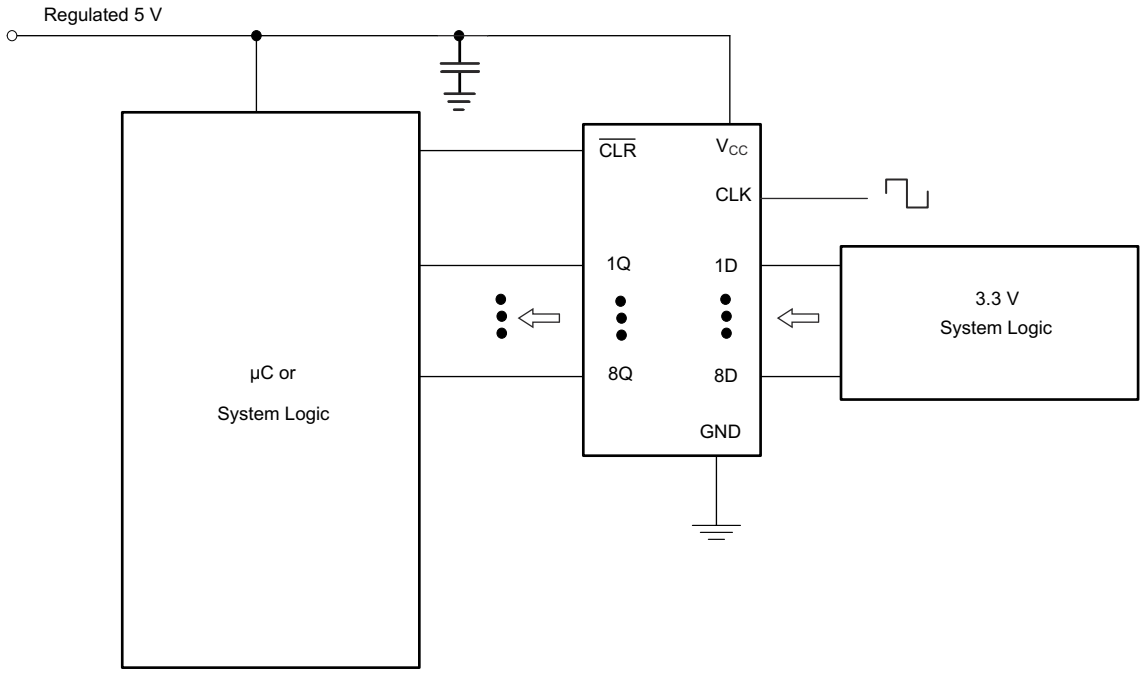


図 8-1. Typical Application Schematic

8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

8.2.2 Detailed Design Procedure

1. Recommended input conditions
   - Rise time and fall time specs: See (Δt/ΔV) in the *セクション 5.3* table.
   - Specified High and low levels: See (V_{IH} and V_{IL}) in the *セクション 5.3* table.
   - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC}
2. Recommend output conditions
   - Load currents should not exceed 25 mA per output and 75 mA total for the part
   - Outputs should not be pulled above V_{CC}

8.2.3 Application Curves

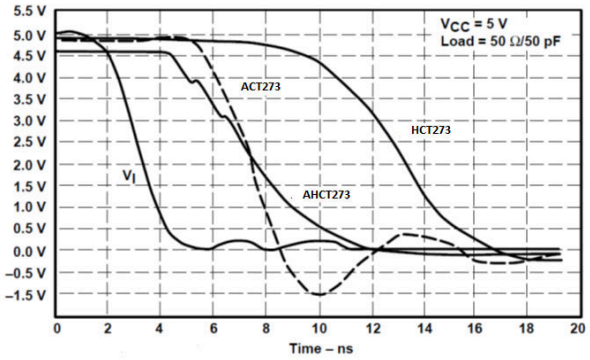


図 8-2. Switching Characteristics Comparison

8.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the *セクション 5.3* table.

Each V_{CC} pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 µF is recommended. If there are multiple V_{CC} pins, 0.01 µF or 0.022 µF is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 µF and 1 µF are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

8.4 Layout

8.4.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified in 図 8-3 are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally inputs will be tied to GND or V_{CC}, whichever makes more sense or is more convenient. It is generally acceptable to float outputs unless the part is a transceiver.

8.4.2 Layout Example

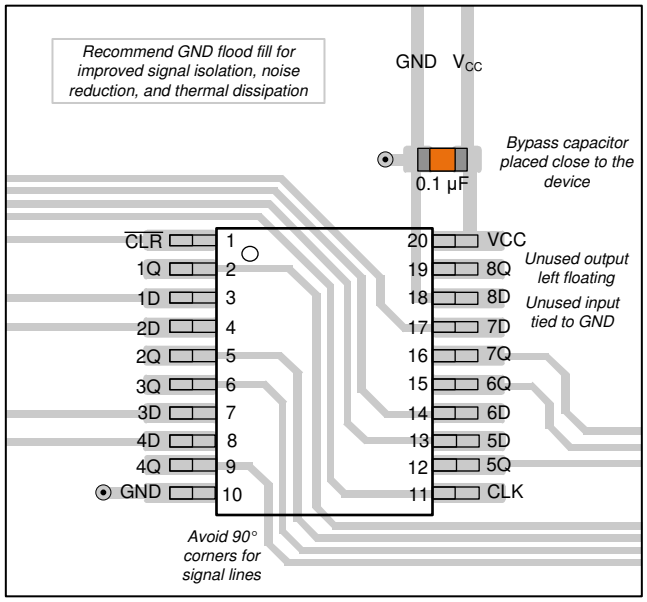


図 8-3. Layout Diagram

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

表 9-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74AHCT273	Click here	Click here	Click here	Click here	Click here

9.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。 変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

9.3 サポート・リソース

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すべての商標は、それぞれの所有者に帰属します。

9.5 静電気放電に関する注意事項

この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

9.6 用語集

テキサス・インスツルメンツ用語集　　この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

Changes from Revision F (July 2014) to Revision G (August 2024) **Page**

- 「パッケージ情報」表にパッケージ サイズを追加 1
- データシート全体にわたって軍用デバイスへの参照を削除 1
- Updated RθJA values: PW = 104.7 to 116.8, DB = 98.7 to 87.2, DW = 81.8 to 81.1, NS = 79.4 to 77.6; Updated PW, DB, DW, and NS packages for RθJC(top), RθJB, ΨJT, ΨJB, and RθJC(bot), all values in °C/W 5
- Updated *Layout Example* image 12

Changes from Revision E (April 2002) to Revision F (July 2014) **Page**

- ドキュメントを テキサス・インスツルメンツの新しいデータシート規格に更新 1
- 「注文情報」表を削除。 1
- 「アプリケーション」を追加。 1
- Added Handling Ratings table. 4
- Changed MAX operating temperature to 125°C in Recommended Operating Conditions table. 4
- Added Typical Characteristics section. 6
- Added Application and Implementation section. 10

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

重要なお知らせと免責事項

テキサス・インスツルメンツは、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

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郵送先住所:Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74AHCT273DBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(AHCT273, HB273)	Samples
SN74AHCT273DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	-40 to 125	AHCT273	
SN74AHCT273DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT273	Samples
SN74AHCT273N	ACTIVE	PDIP	N	20	20	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 125	SN74AHCT273N	Samples
SN74AHCT273NSR	ACTIVE	SOP	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT273	Samples
SN74AHCT273PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB273	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

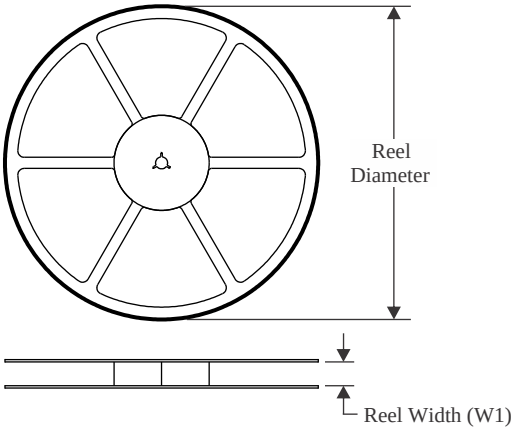
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

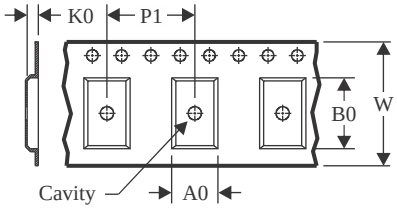
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

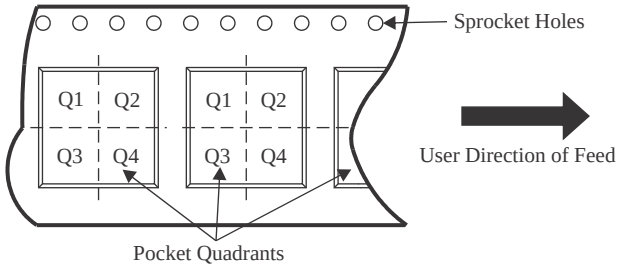


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

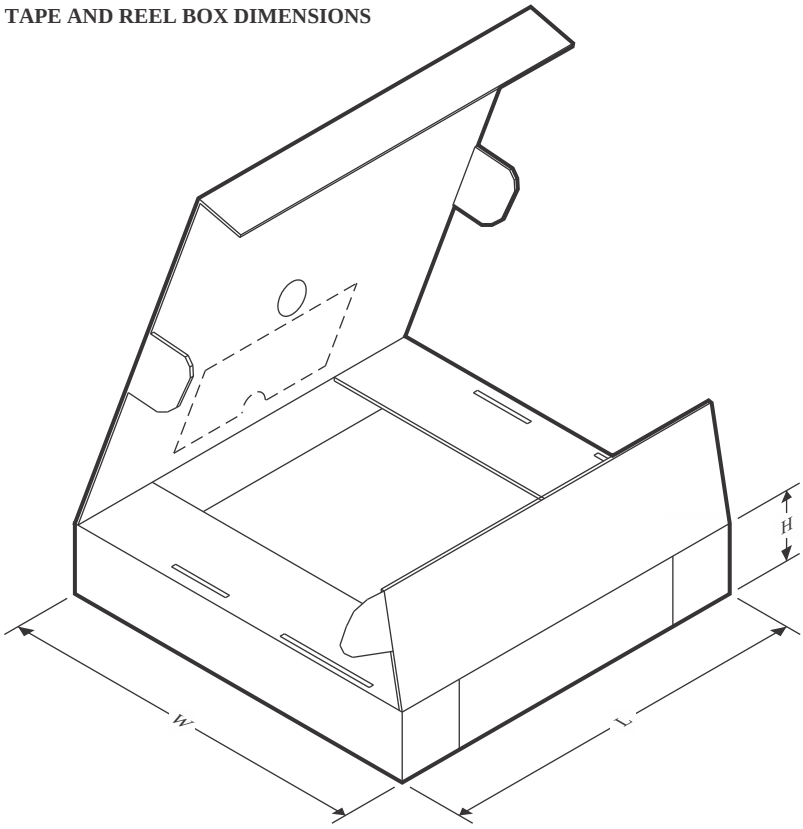
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT273DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AHCT273DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AHCT273DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AHCT273DWR	SOIC	DW	20	2000	330.0	24.4	10.9	13.3	2.7	12.0	24.0	Q1
SN74AHCT273NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AHCT273NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74AHCT273PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

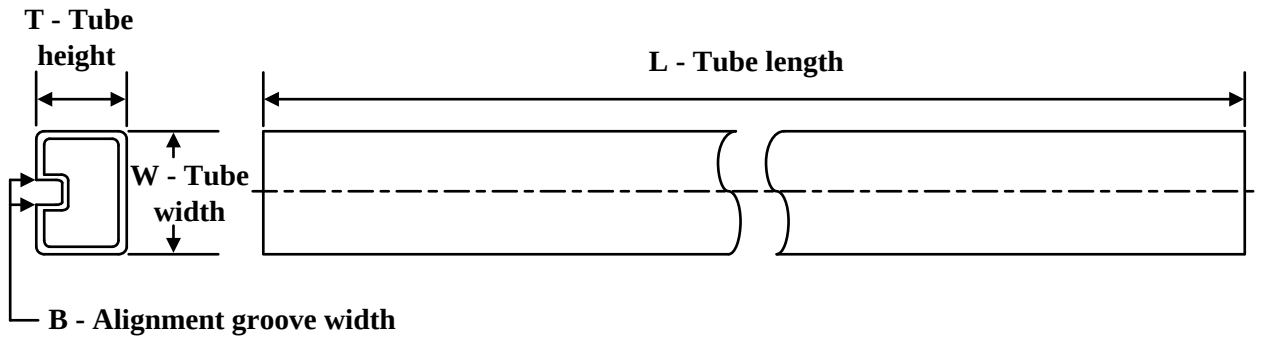
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT273DBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74AHCT273DBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74AHCT273DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74AHCT273DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74AHCT273NSR	SOP	NS	20	2000	367.0	367.0	45.0
SN74AHCT273NSR	SOP	NS	20	2000	356.0	356.0	41.0
SN74AHCT273PWR	TSSOP	PW	20	2000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

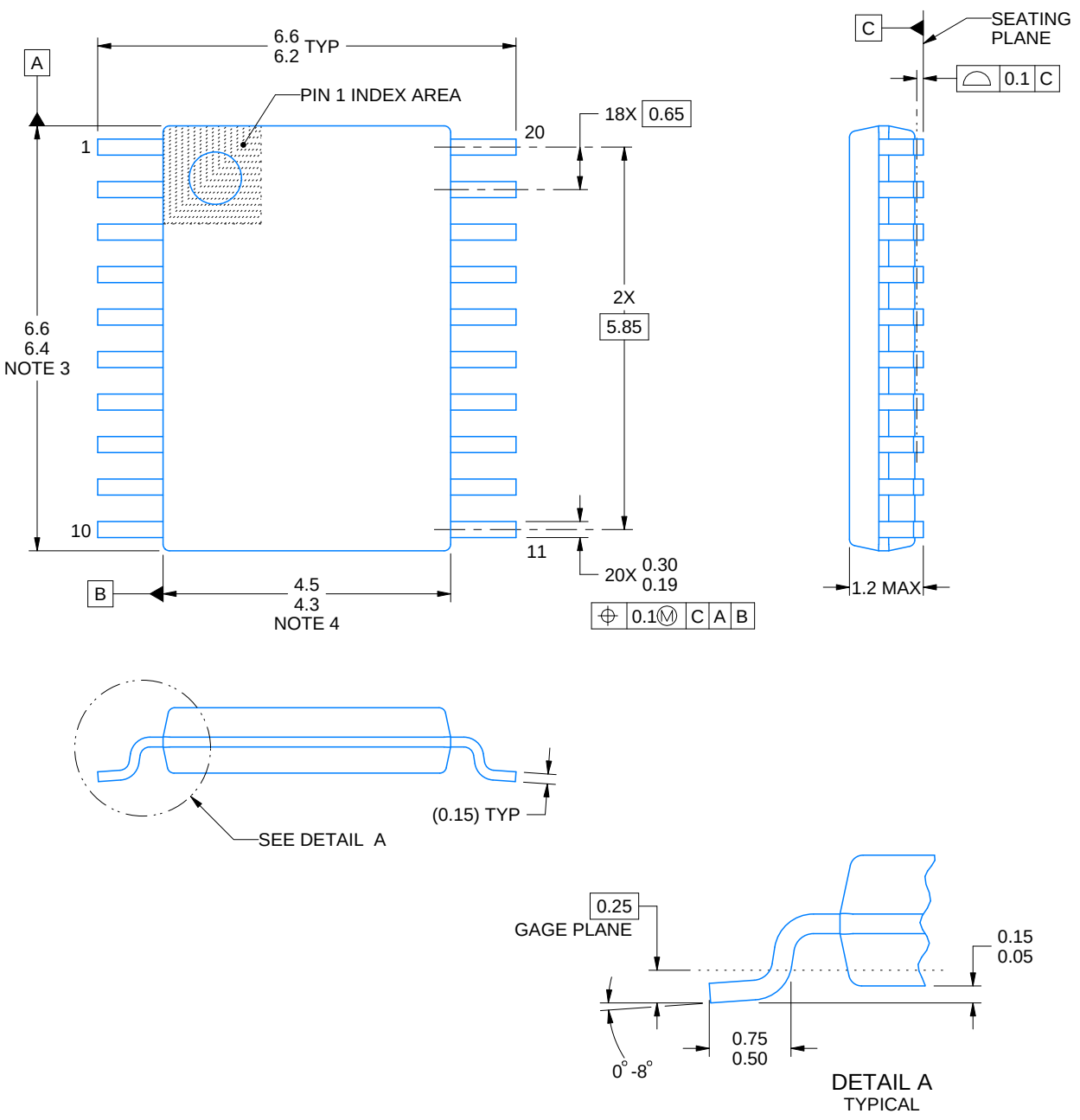
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74AHCT273N	N	PDIP	20	20	506	13.97	11230	4.32

PACKAGE OUTLINE

PW0020A

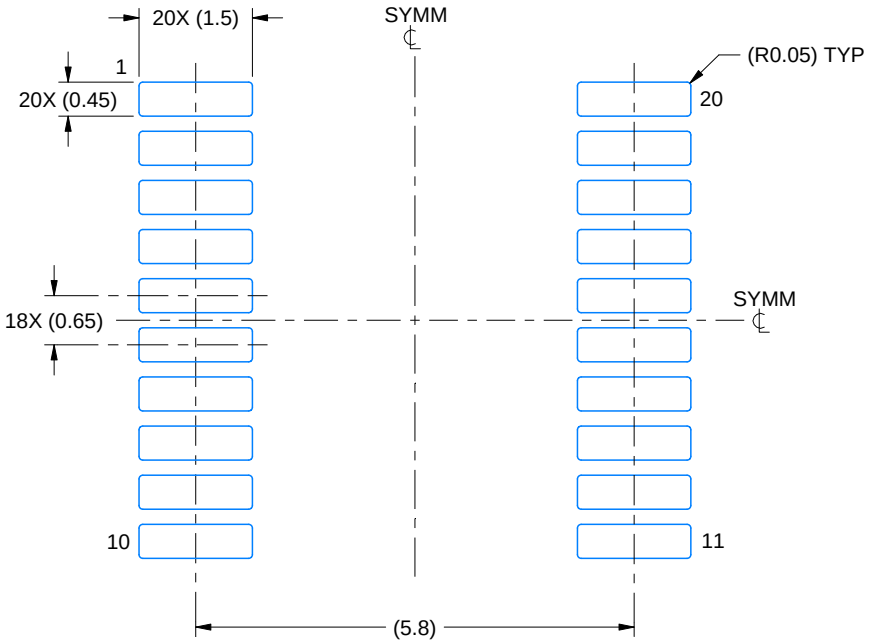
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



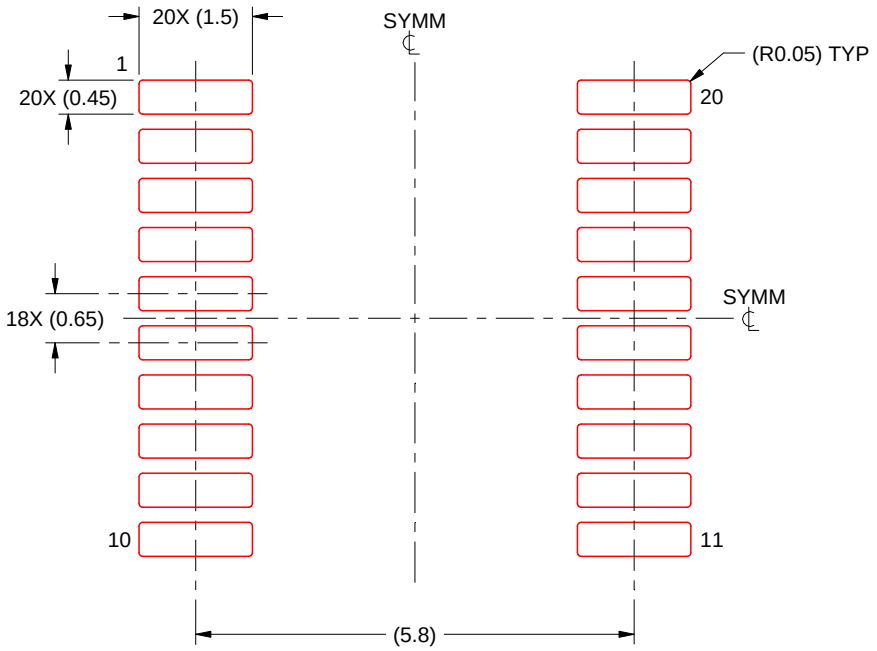
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

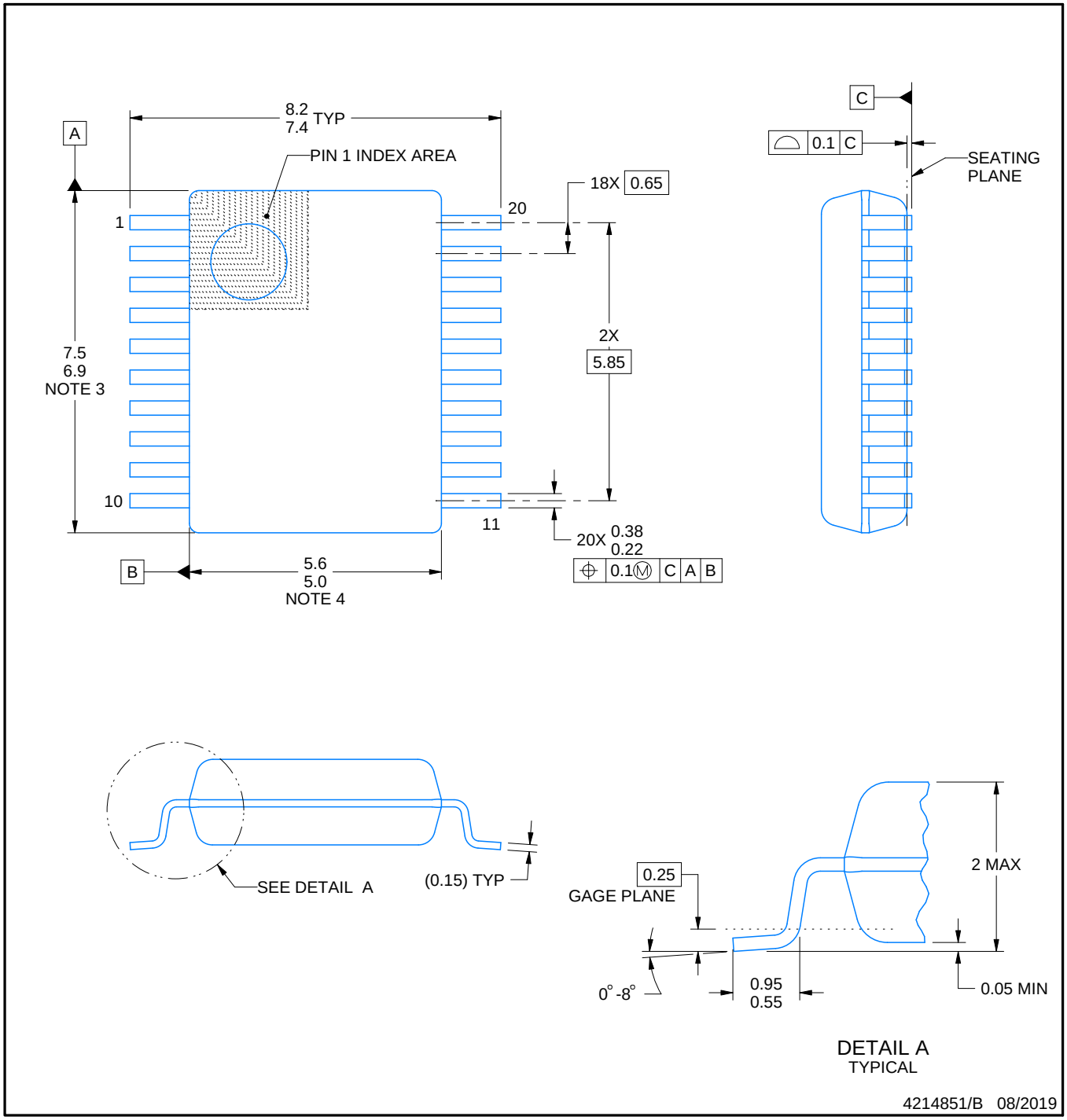
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DB0020A

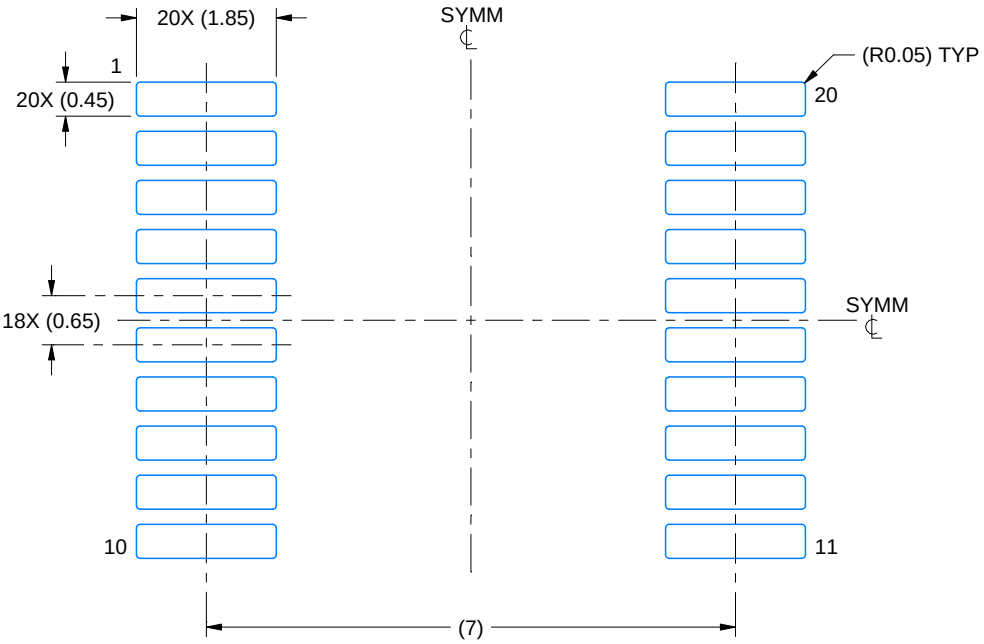
SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

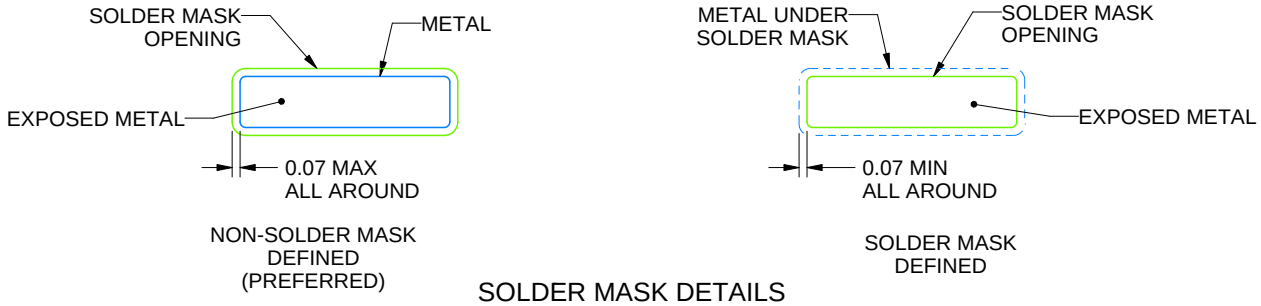


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

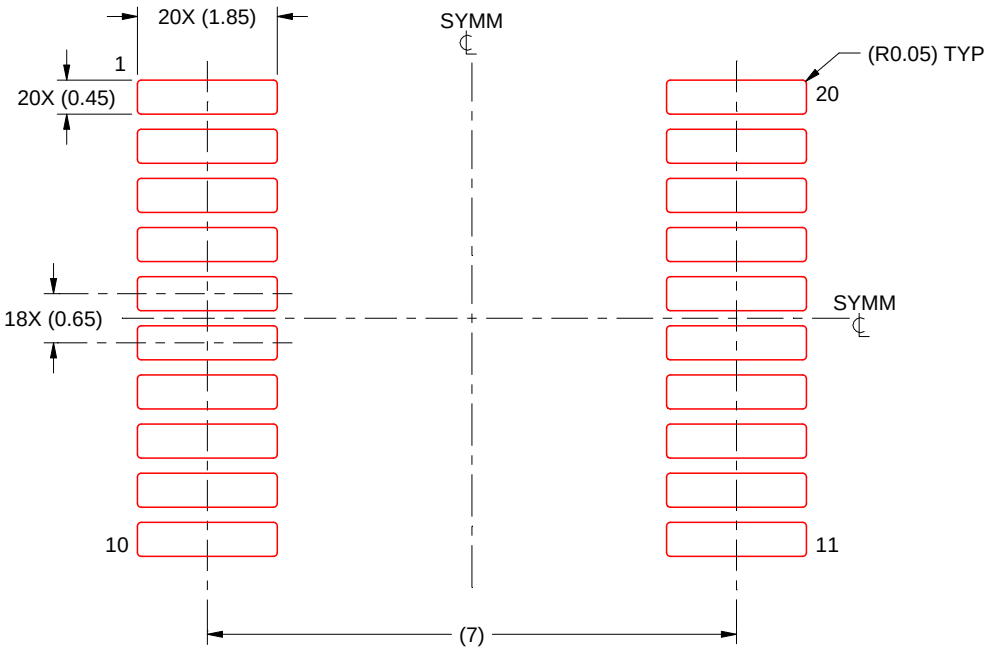
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

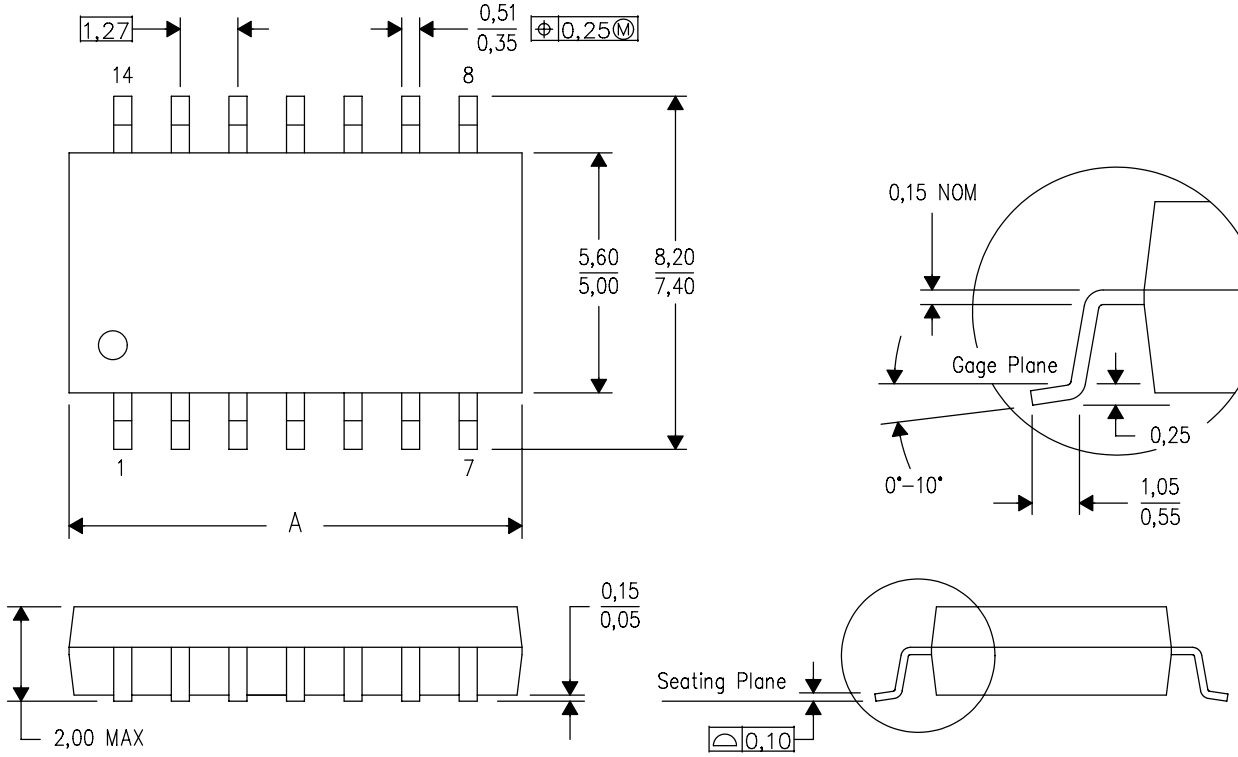
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

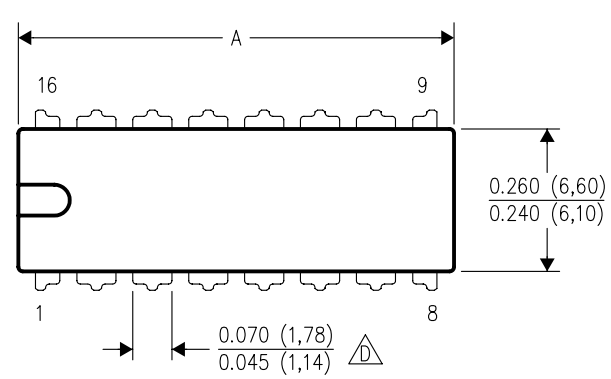
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

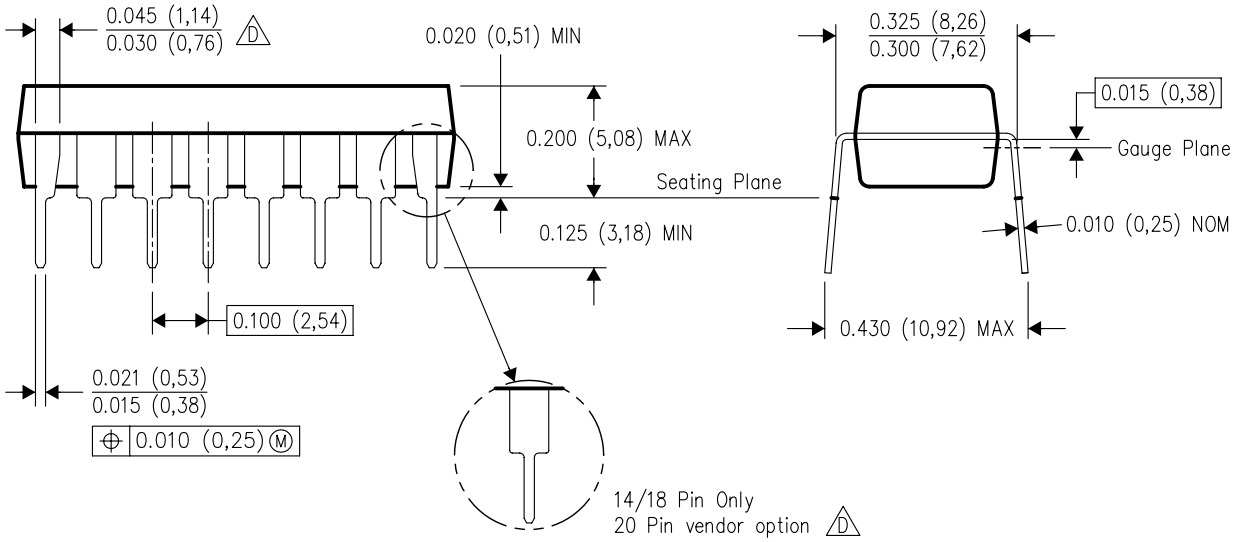
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

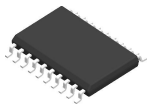


DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

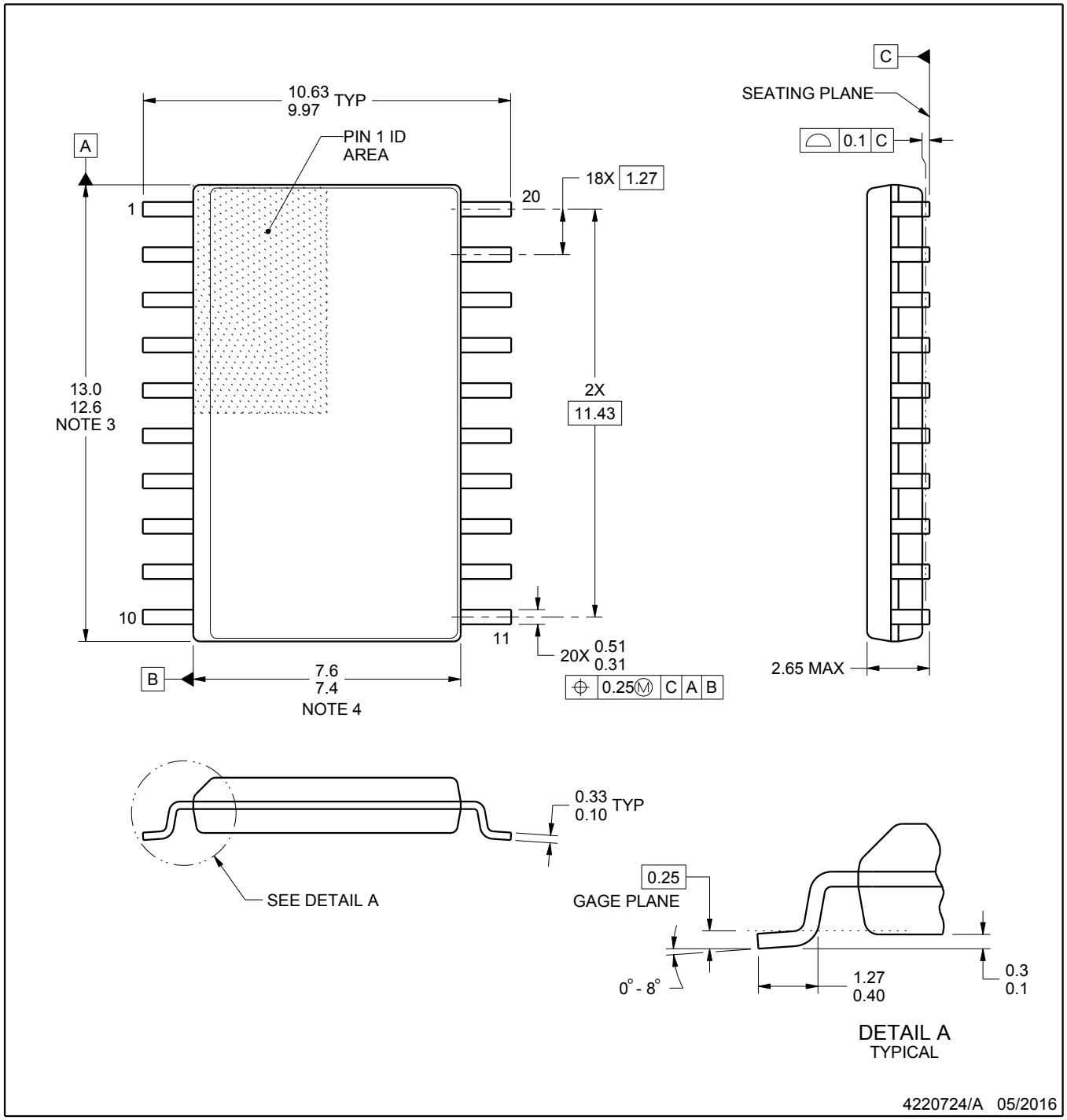


PACKAGE OUTLINE

DW0020A

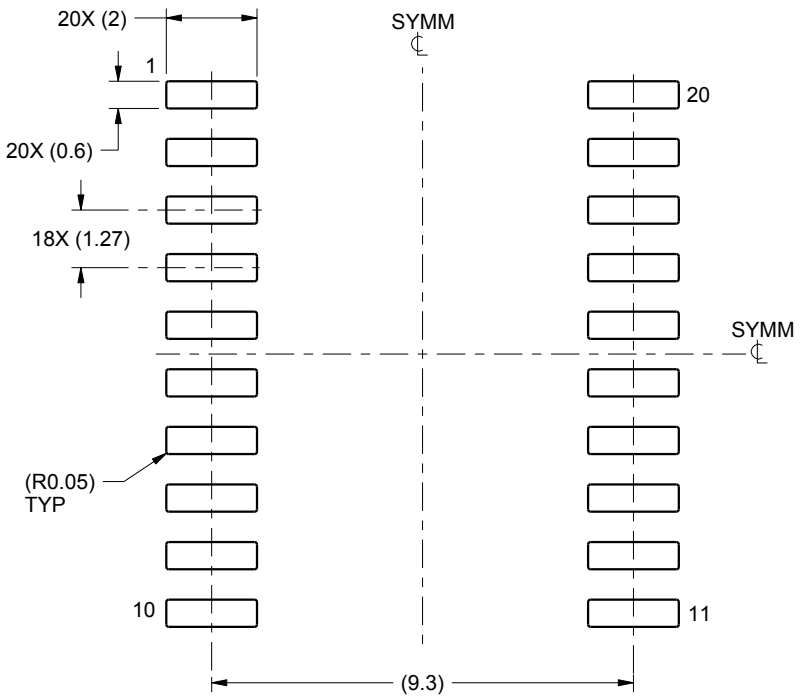
SOIC - 2.65 mm max height

SOIC

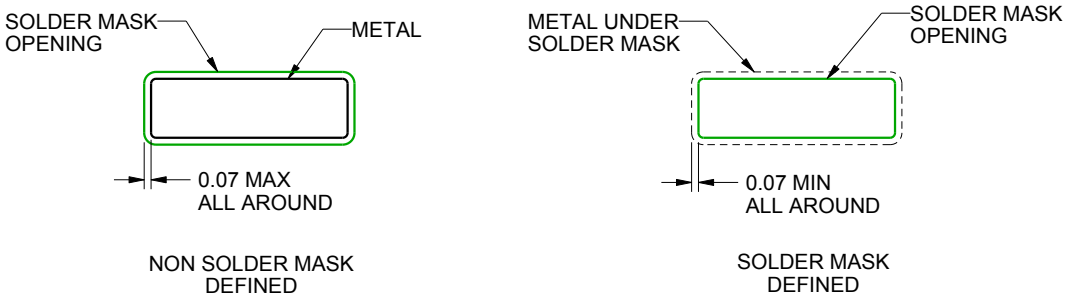


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

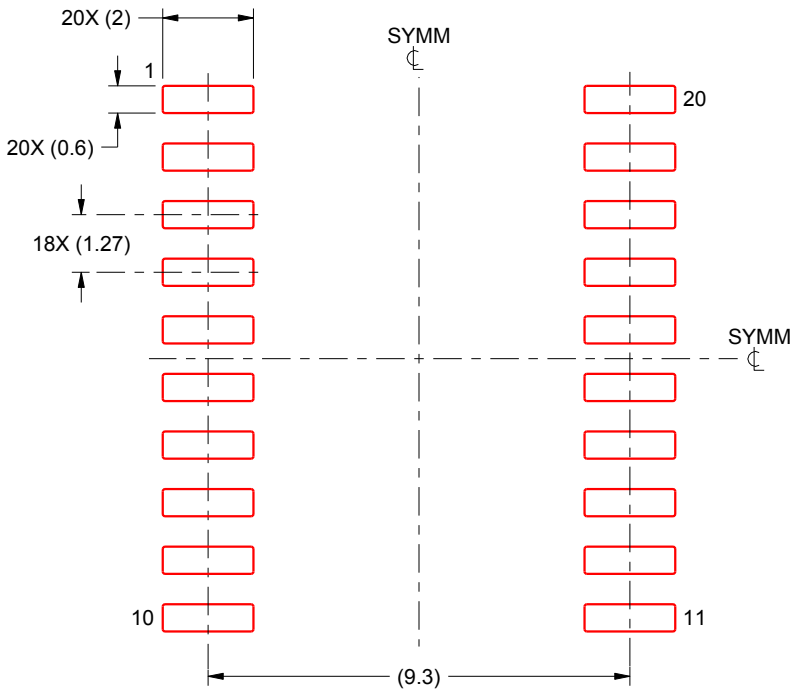


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

重要なお知らせと免責事項

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郵送先住所：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265